SN74LVTH16245A-Q1 3.3-V ABT 16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCAS772C - JUNE 2004 - REVISED JANUARY 2008

 Qualified for Automotive Applications Member of the Texas Instruments 	DGG OR DL PACKAGE (TOP VIEW)
Widebus™ Family	1DIR 1 48 1 0E
 State-of-the-Art Advanced BiCMOS 	1DIR 1 48 10E 1B1 2 47 1A1
Technology (ABT) Design for 3.3-V	1B2 3 46 1A2
Operation and Low Static-Power	GND 4 45 GND
Dissipation	1B3 05 44 11 1A3
 Supports Mixed-Mode Signal Operation 	1B4 6 43 1A4
(5-V Input and Output Voltages With	V _{CC} [7 42] V _{CC}
3.3-V V _{CC})	1B5 [8 41] 1A5
Supports Unregulated Battery Operation	1B6 9 40 1A6
Down To 2.7 V	GND 10 39 GND
Typical V _{OLP} (Output Ground Bounce)	1B7 11 38 11A7
$< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$	1B8 12 37 1 1A8
	2B1 13 36 2A1
 Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise 	2B2 14 35 2A2
	GND 15 34 GND
Flow-Through Architecture Optimizes PCB	2B3 1 16 33 2A3
Layout	2B4 [17 32] 2A4
 I_{off} and Power-Up 3-State Support Hot 	V _{CC}
Insertion	2B5 1 19 30 1 2A5
 Bus Hold on Data Inputs Eliminates the 	2B6 🛮 20 29 🗓 2A6
Need for External Pullup/Pulldown	GND
Resistors	2B7 🛮 22 27 🗓 2A7
 Latch-Up Performance Exceeds 500 mA Per 	2B8 🛮 23 26 🗓 2A8
JESD 17	2DIR 🛮 24 25 🗓 2 0E

description/ordering information

The SN74LVTH16245A is a 16-bit (dual-octal) noninverting 3-state transceiver designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the devices so that the buses are isolated.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with bus-hold circuitry is not recommended.



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Widebus is a trademark of Texas Instruments.



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description/ordering information (continued)

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} shall be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

ORDERING INFORMATION†

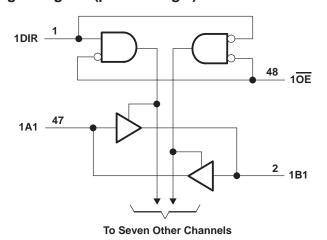
TA	PACKA	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SSOP – DL	Tape and reel	CLVTH16245AQDLRQ1§	LH16245AQ1
	TSSOP – DGG	Tape and reel	CLVTH16245AQDGGRQ1	LH16245AQ1

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

FUNCTION TABLE (each 8-bit section)

INP	UTS	ODED ATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

logic diagram (positive logic)



2DIR 24 25 2OE 25 2OE 281

To Seven Other Channels

TEXAS INSTRUMENTS

[‡]Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

[§] Product Preview

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	
Voltage range applied to any output in the high state, VO (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, I _O	96 mA
Current into any output in the high state, I _O (see Note 2)	48 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	70°C/W
DL package	63°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

				N74LVTH	I16245AQ		
			T _A = -40°C T	O 125°C	T _A = -40°C	TO 85°C	UNIT
			MIN	MAX	MIN	MAX	
VCC	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage	2		2		V	
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage			5.5		5.5	V
loh	High-level output current			-24		-32	mA
loL	Low-level output current			24		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔVCC	Power-up ramp rate		200		200		μs/V

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					SN	174LVTH	116245AQ				
PA	RAMETER	TEST CO	NDITIONS	-40°C	TO 125°	С	-40°C	TO 85°C		UNIT	
				MIN	TYP [†]	MAX	MIN	TYP [†]	MAX		
VIK		$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} - 0.2			V _{CC} - 0.2				
. ,		V _{CC} = 2.7 V,	I _{OH} = -8 mA	2.4			2.4			.,	
VOH			I _{OH} = -24 mA	2						V	
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2				
		V 07V	I _{OL} = 100 μA			0.2			0.2		
		V _{CC} = 2.7 V	I _{OL} = 24 mA			0.5			0.5		
VOL			I _{OL} = 16 mA			0.4			0.4	V	
		V _{CC} = 3 V	I _{OL} = 32 mA						0.5		
			I _{OL} = 64 mA						0.55		
		V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10	μΑ	
Ц			V _I = 5.5 V			20			20		
	A or B ports‡	V _{CC} = 3.6 V	VI = VCC			5			1		
			V _I = 0			-5			-5		
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ	
		., .,	V _I = 0.8 V	75			75				
ha in	A or B ports	V _{CC} = 3 V	V _I = 2 V	-75			-75			μΑ	
I(hold)	A of B ports	V _{CC} = 3.6 V§,	V _I = 0 V to 3.6 V						500 -750	μА	
lozpu		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, V_{O}	= 0.5 V to 3 V,			±100			±100	μА	
lozpd		$\frac{V_{CC}}{OE}$ = 1.5 V to 0, V _O	= 0.5 V to 3 V,			±100			±100	μА	
			Outputs high			0.19			0.19		
ICC		$V_{CC} = 3.6 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low			5			5	mA	
		AL = ACC OLOUP	Outputs disabled			0.19			0.19		
ΔICC¶		V _{CC} = 3 V to 3.6, One Other inputs at V _{CC} o		_	0.2		_	0.2	mA		
Ci		V _I = 3 V or 0			4			4		pF	
C _{io}		V _O = 3 V or 0			10			10		рF	

[†] All typical values are at V_{CC} = 3.3 V, T_{A} = 25°C. ‡ Unused pins at V_{CC} or GND



[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another. ¶ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

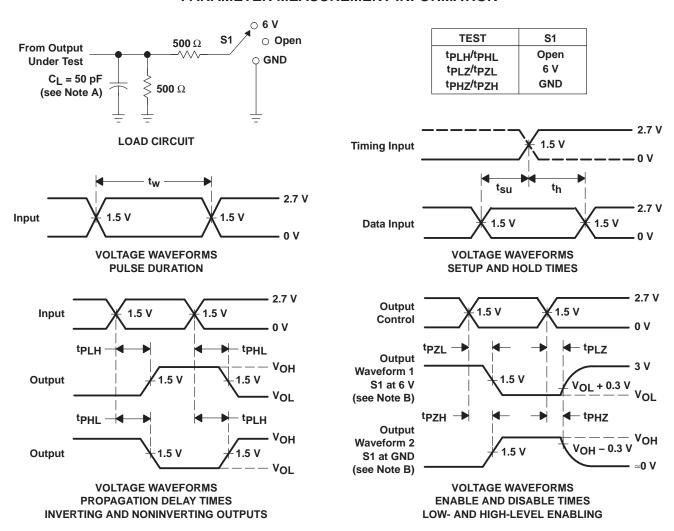
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

			SN74LVTH16245AQ									
	FDOM	T 0		–40°C TO 125°C				−40°C TO 85°C				
PARAMETER	FROM (INPUT)	TO (OUTPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V	
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	0.5	4.5		4.6	1.5	2.3	3.3		3.7	20
t _{PHL}	AUB	BOIA	0.5	4.4		3.9	1.3	2.1	3.3		3.5	ns
^t PZH	ŌĒ	A or B	0.5	6.5		6.6	1.5	2.8	4.5		5.3	
t _{PZL}	OE	A or B	0.5	5.4		6.2	1.6	2.9	4.6		5.2	ns
^t PHZ	ŌĒ	A D	1	6.8		7	2.3	3.7	5.1		5.5	
tPLZ		A or B	1	6.2		6.3	2.2	3.5	5.1		5.4	ns
^t sk(o)						·			0.5		0.5	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

TEXAS INSTRUMENTS

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
CLVTH16245AQDGGRQ1	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LH16245AQ1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LVTH16245A-Q1:



PACKAGE OPTION ADDENDUM

10-Dec-2020

• Catalog: SN74LVTH16245A

• Enhanced Product: SN74LVTH16245A-EP

• Military: SN54LVTH16245A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 12-May-2017

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVTH16245AQDGGRQ1	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

www.ti.com 12-May-2017



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CLVTH16245AQDGGRQ1	TSSOP	DGG	48	2000	367.0	367.0	45.0	



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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